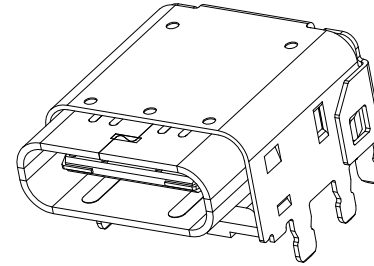
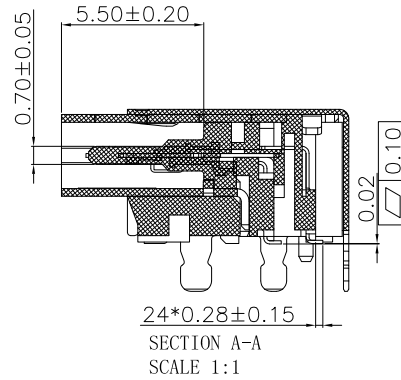
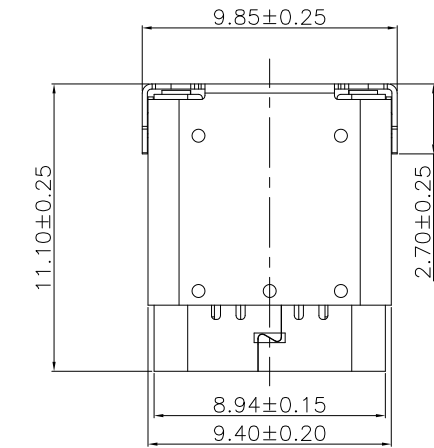


HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	Tim	BENDEE	BENDEE	20-07-11

A

A



料号备注

CT 3 F 039 M X X X X X X X X

A=PACK-R0132

R=PACK-R0125

12=半金雾锡10"

13=半金雾锡30"

14=半金雾锡50"

15=半金雾锡150"

16=半金雾锡300"

R=ROHS2.0标准

W=无卤+ROHS2.0

H=REACH标准

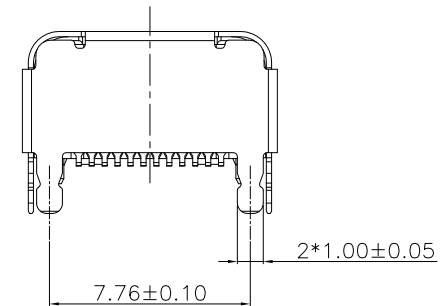
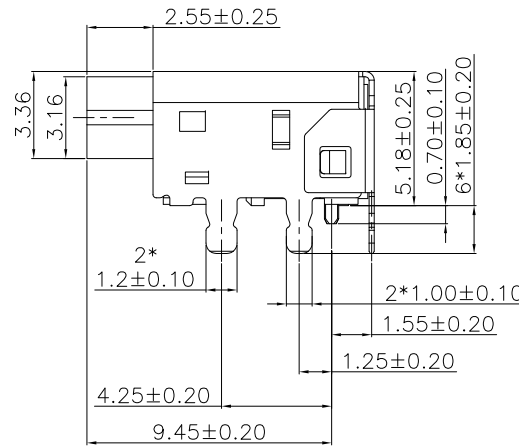
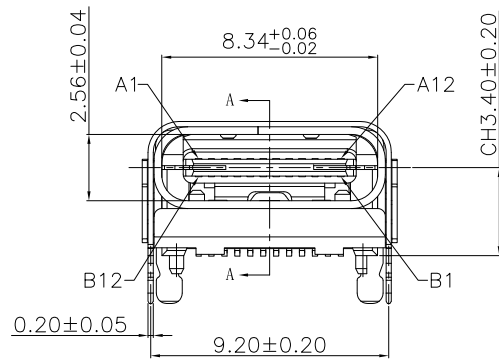
B=盐雾24H

C=盐雾48H

00=LCP黑不锈钢壳镀银

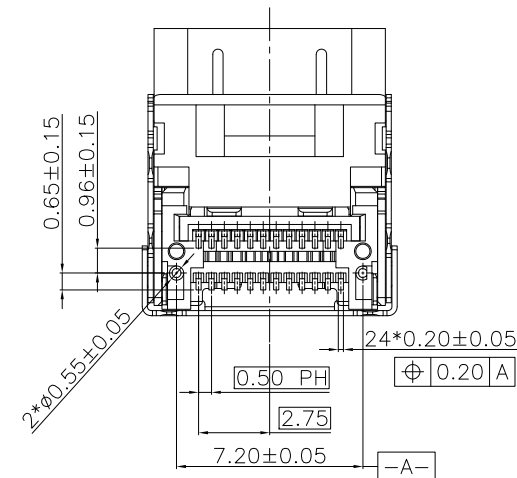
B

B



C

C



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Dong Guan XingKeJieXin Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED
TOLERANCES

X. +/- METRIC 0.30
.X +/- 0.25
.XX +/- 0.15
FRACTIONS +/-
ANGLES +/- 2.00'

DIMENSIONS
(METRIC) (MM)

APPROVAL

制图 Tim

审核

核准

文件位置

日期

2020.07.11

品名

规格

料号

字张

工程图号:

比例

1 : 1

USB 3.1 GEN2 TYPE C(TBT) RECEPTACLE
24P 双排SMT CH3.4 L11.10

SEE TABLE

DWG-CTCF-039

版本:

A0

状态码 A 页数 1 OF 2

4

5

6

1

2

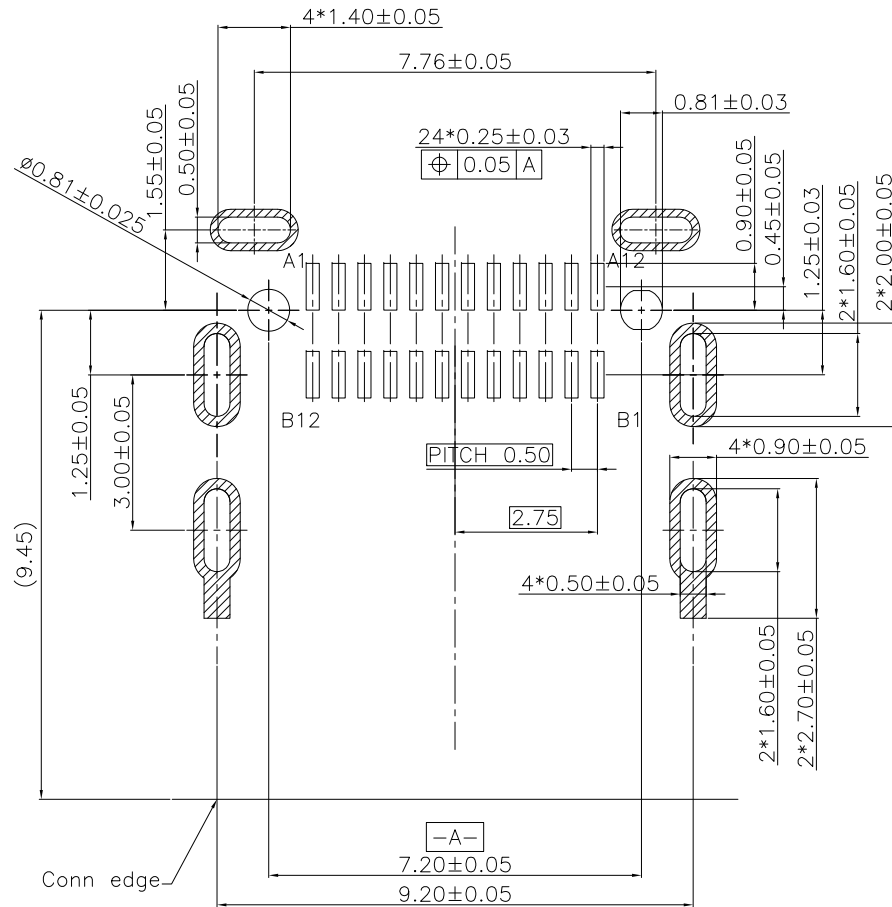
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D

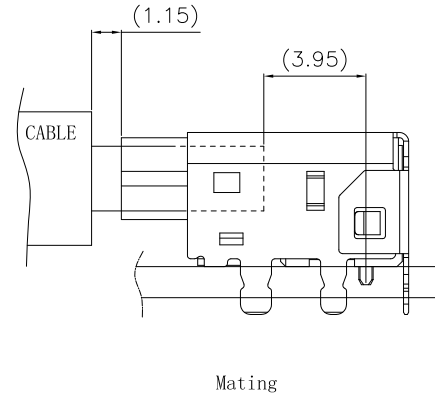
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HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	Tim	BENDEE	BENDEE	20-07-11



RECOMMENDED PCB LAYOUT(TOP) SCALE 2:1
THICKNESS=1.2mm



Specifications:

1.0 Electrical performance:

1.1 Contact resistance: 40mΩ max for initial.
10mΩ change after test. measure at 20mv, 100mA.

1.2 Dielectric withstanding voltage:AC 100V(rms).

1.3 Insulation resistance:100MΩ min.

1.4 Contact current rating:

3A for Vbus pin;1.25A for Vconn and GND pin;0.25A for all the other pin.

1.5 Voltage: 5 Vac (rms).

2.0 mechanical performance:

2.1 Mating force:5~20N

2.2 Unmating force:8~20N Initial test,
6~20N After test

2.3 Durability:10,000 cycles.

3.0 Environmental performance:

3.1 Temperature range:

3.2 Operating temperature:-25°to+85°.

3.3 Storage temperature:-20°to+60°.

4.0 Material:

4.1 Housing:LCP Black,UL94-V0.

4.2 Contact:C7025,T=0.12mm

4.3 Mid-plate: SUS301,T=0.15mm

4.4 Shell-in:SUS304 T=0.30mm

4.5 Shell-out:SUS301 T=0.20mm

5.0 Plating specification:

5.1 Contact:Au(see table) plated on contact area
Matte Tin plated 100u"min on solder
area;Nickel 50u"min underplating over all.

5.2 Shell-out: Nickel 30u"min plating over all.

料号备注

A=PACK-R0132

R=PACK-R0125

CT 3 F 039 M XX X XX X X

12=半金雾锡10"
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14=半金雾锡50"
15=半金雾锡150"
16=半金雾锡300"

00=LCP黑不锈钢壳电镀

R=ROHS2.0标准

W=无卤+ROHS2.0

H=REACH标准

B=盐雾24H

C=盐雾48H

A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

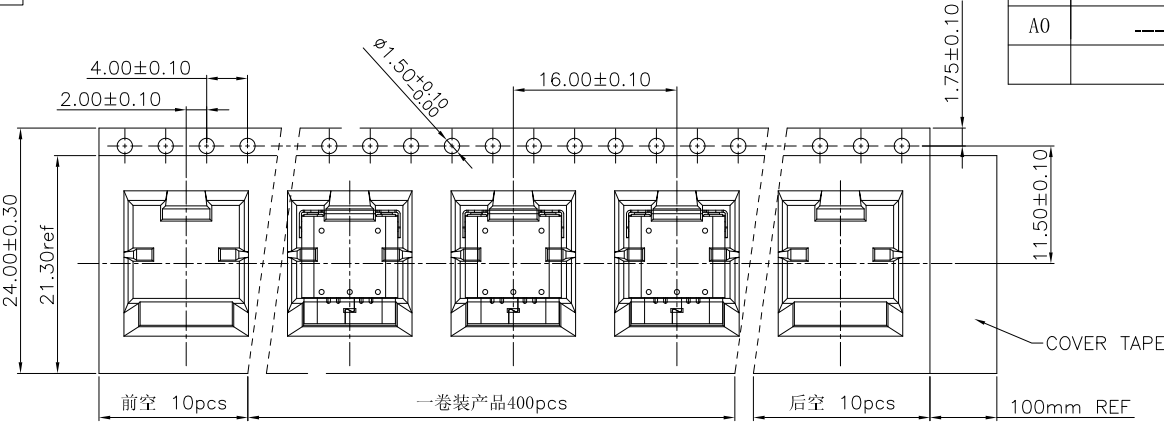


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UNLESS OTHERWISE SPECIFIED TOLERANCES		APPROVAL	日期	品名	规格
X.	+/-	制图	Tim	2020.07.11	
.X	+/-	审核			
.XX	+/-	核准			
FRACTIONS	+/-	文件位置			
ANGLES	+/-				
DIMENSIONS		ANGLE OF PROJECTION		字张	工程图号:
(METRIC)	(MM)			A4	DWG-CTCF-039
				比例	1 : 1
				状态码	A
				页数	2 OF 2

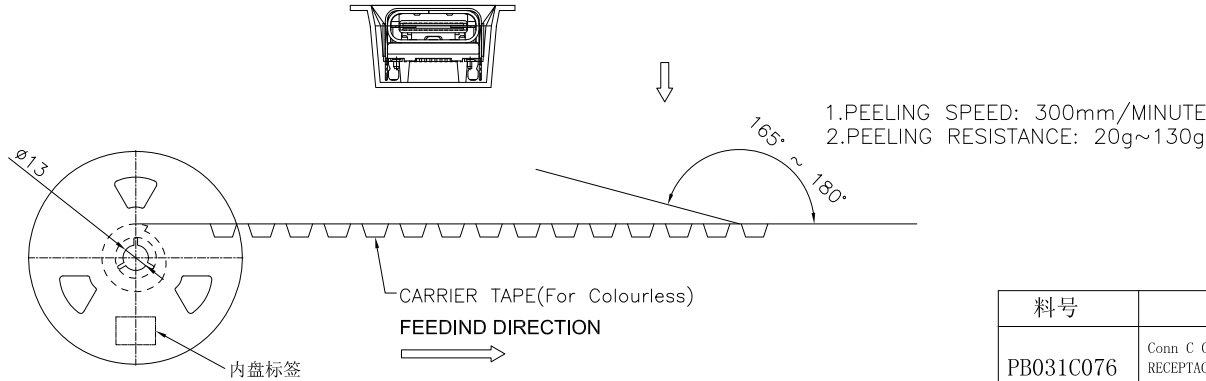
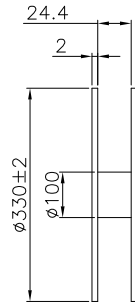
HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	---	NEW DRAWING	Tim	BENDEE	BENDEE	20-07-10



责任业务签字:

包 装 信 息	
每盘产品数	400pcs
每箱卷盘数	10卷
每箱产品数	4000pcs
产品单重	/
每箱净重	/
每箱毛重	以实际为准



料号	品名	规格	单位	用量
PB031C076	Conn C GEN2 TYPE C RECEPTACLE 24P 双排SMT CH3.4 L11.10-GJ 载带	Φ 330, 载带W=24mm PH=16mm T=0.5mm PET透明 无卤	SET	1/400
PB031C038	上封带	自粘式透明, T=0.05mm, W=20.7mm	M	9/400
PE031C005	防水袋	80*80CM, T=0.05mm	PCS	1/4000
PP011C027	三角板	10cm*10cm*13cm, H30cm	PCS	4/4000
PP011C009	纸板	33*33CM A=B, 纸板	PCS	2/4000
PP001C056	外箱	外箱K=K, 外径35*35*32CM	PCS	1/4000



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DongGuan XingKeJieXin Electronics Co., Ltd

所有物料与操作均符合ROHS管制标准	APPROVAL	日期	品名	USB 3.1 GEN2 TYPE C RECEPTACLE 24P 双排SMT CH3.4 L11.10		
	制图 Tim	2020.07.10	规格			
	审核		料号			
	核准		文件位置			
	ANGLE OF PROJECTION		字张 A4	工程图号: PACK-R0132	版本: A0	
			比例 1 : 1	状态码 C	页数 1 OF 1	

